150 mA, Wide Input Range, Voltage Regulator

The NCP4641 is a CMOS 150 mA linear voltage regulator with high input voltage and ultra-low supply current. It incorporates multiple protection features such as peak current limit, short circuit current limit and thermal shutdown to ensure a very robust device.

A high maximum input voltage tolerance of 50 V and a wide temperature range make the NCP4641 suitable for a variety of demanding applications.

Features

- Operating Input Voltage Range: 4 V to 36 V
- Output Voltage Range: 2.0 to 12.0 V (0.1 steps)
- ±2% Output Voltage Accuracy
- Output Current: min 150 mA ($V_{IN} = 8 V$, $V_{OUT} = 5 V$)
- Line Regulation: 0.05%/V
- Peak Current Limit Circuit
- Short Current Limit Circuit
- Thermal Shutdown Circuit
- Available in SOT-89-5 and SOIC6-TL Package
- These are Pb-Free Devices

Typical Applications

- Power source for home appliances
- Power source for car audio equipment, navigation system
- Power source for notebooks, digital TVs, cordless phones and private LAN systems
- Power source for office equipment machines such as copiers, printers, facsimiles, scanners, projectors, etc.



Figure 1. Typical Application Schematic



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MARKING DIAGRAMS





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SOT-89 5

CASE 528AB

XXXX = Specific Device Code MM = Date Code

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 12 of this data sheet.



Figure 2. Simplified Schematic Block Diagram

| Pin No.<br>SOT89 | Pin No.<br>SOIC6-TL | Pin Name | Description                                                                        |
|------------------|---------------------|----------|------------------------------------------------------------------------------------|
| 5                | 6                   | VIN      | Input pin                                                                          |
| 2                | 2                   | GND      | Ground pin, all ground pins must be connected together when it is mounted on board |
| 4                | 4                   | GND      | Ground pin, all ground pins must be connected together when it is mounted on board |
| -                | 5                   | GND      | Ground pin, all ground pins must be connected together when it is mounted on board |
| 3                | 3                   | CE       | Chip enable pin ("H" active)                                                       |
| 1                | 1                   | VOUT     | Output pin                                                                         |

#### **PIN FUNCTION DESCRIPTION**

#### **ABSOLUTE MAXIMUM RATINGS**

| Rating                                    | Symbol             | Value                         | Unit |
|-------------------------------------------|--------------------|-------------------------------|------|
| Input Voltage                             | V <sub>IN</sub>    | –0.3 to 50                    | V    |
| Peak Input Voltage (Note 1)               | V <sub>IN</sub>    | 60                            | V    |
| Output Voltage                            | V <sub>OUT</sub>   | $-0.3$ to Vin + 0.3 $\leq 50$ | V    |
| Chip Enable Input                         | V <sub>CE</sub>    | –0.3 to VIN + 0.3 $\leq$ 50   | V    |
| Output Current                            | I <sub>OUT</sub>   | 250                           | mA   |
| Power Dissipation SOT-89                  | P <sub>D</sub> 900 |                               | mW   |
| Power Dissipation SOIC6-TL                |                    | 1700                          |      |
| Junction Temperature                      | TJ                 | -40 to 150                    | °C   |
| Storage Temperature                       | T <sub>STG</sub>   | -55 to 125                    | °C   |
| ESD Capability, Human Body Model (Note 2) | ESD <sub>HBM</sub> | 2000                          | V    |
| ESD Capability, Machine Model (Note 2)    | ESD <sub>MM</sub>  | 200                           | V    |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Duration time = 200 ms

Duration time = 200 ms
This device series incorporates ESD protection and is tested by the following methods: ESD Human Body Model tested per AEC-Q100-002 (EIA/JESD22-A114) ESD Machine Model tested per AEC-Q100-003 (EIA/JESD22-A115) Latchup Current Maximum Rating tested per JEDEC standard: JESD78.

#### **THERMAL CHARACTERISTICS**

| Rating                                                                   | Symbol          | Value | Unit |
|--------------------------------------------------------------------------|-----------------|-------|------|
| Thermal Characteristics, SOT-89<br>Thermal Resistance, Junction-to-Air   | $R_{\theta JA}$ | 111   | °C/W |
| Thermal Characteristics, SOIC6-TL<br>Thermal Resistance, Junction-to-Air | $R_{\theta JA}$ | 59    | °C/W |

| Parameter                               | Test Conditions                                                             |                                                          | Symbol              | Min   | Тур  | Max      | Unit              |
|-----------------------------------------|-----------------------------------------------------------------------------|----------------------------------------------------------|---------------------|-------|------|----------|-------------------|
| Operating Input Voltage                 |                                                                             |                                                          | Vin                 | 4     |      | 36       | V                 |
| Output Voltage                          | V <sub>IN</sub> = Vout + 3                                                  | V, I <sub>OUT</sub> = 1 mA                               | Vout                | x0.98 |      | x1.02    | V                 |
| Output Voltage Temp. Coefficient        | V <sub>IN</sub> = Vout + 3 V, I <sub>OU</sub><br>10                         | <sub>IT</sub> = 1 mA, T <sub>A</sub> = −40 to<br>5°C     |                     |       | ±100 |          | ppm/°C            |
| Line Regulation                         | V <sub>IN</sub> = Vout + 1.5 V                                              | to 36 V, I <sub>OUT</sub> = 1 mA                         | Line <sub>Reg</sub> |       | 0.05 | 0.20     | %/V               |
| Load Regulation                         | $V_{IN} = V_{OUT} + 3 V,$                                                   | $2.0~\text{V} \leq \text{V}_{\text{OUT}} < 5.0~\text{V}$ | Load <sub>Reg</sub> |       | 10   | 25       | mV                |
|                                         | lout = 1 mA to 40 mA                                                        | $5.0~V \leq V_{OUT} < 12.0~V$                            |                     |       | 20   | 35       |                   |
| Dropout Voltage                         | I <sub>OUT</sub> = 20 mA                                                    | $2.0~\text{V} \leq \text{V}_{OUT} < 3.7~\text{V}$        | Vdo                 |       |      | (Note 3) | V                 |
|                                         |                                                                             | $3.7 \text{ V} \le \text{V}_{OUT} < 4.0 \text{ V}$       |                     |       | 0.35 | 0.60     |                   |
|                                         |                                                                             | $4.0 \text{ V} \le \text{V}_{OUT} < 5.0 \text{ V}$       |                     |       | 0.25 | 0.40     |                   |
|                                         |                                                                             | $5.0~V \leq V_{OUT} < 12.0~V$                            |                     |       | 0.20 | 0.35     |                   |
| Output Current                          | V <sub>IN</sub> = Vout + 3 V                                                | $2.0~\text{V} \leq \text{V}_{\text{OUT}} < 3.0~\text{V}$ | Ιουτ                | 100   |      |          | mA                |
|                                         |                                                                             | $3.0 \text{ V} \le \text{V}_{OUT} < 5.0 \text{ V}$       |                     | 120   |      |          |                   |
|                                         |                                                                             | $5.0~V \leq V_{OUT} < 12.0~V$                            |                     | 150   |      |          |                   |
| Short Current Limit                     | V <sub>OUT</sub>                                                            | - = 0 V                                                  | I <sub>SC</sub>     |       | 50   |          | mA                |
| Quiescent Current                       | V <sub>IN</sub> = Vout + 3                                                  | V, IOUT = 0 mA                                           | lq                  |       | 9    | 20       | μA                |
| Standby Current                         | V <sub>IN</sub> = 36 V                                                      | , V <sub>CE</sub> = 0 V                                  | Istb                |       | 0.1  | 1        | μA                |
| CE Pin Threshold Voltage                | CE Input \                                                                  | /oltage "H"                                              | VCEH                | 1.5   |      | 1        | V                 |
|                                         | CE Input V                                                                  | Voltage "L"                                              | VCEL                |       |      | 0.3      |                   |
| Thermal Shutdown Temperature            |                                                                             |                                                          | T <sub>SD</sub>     |       | 150  |          | °C                |
| Thermal Shutdown Release<br>Temperature |                                                                             |                                                          | T <sub>SR</sub>     |       | 125  |          | °C                |
| Power Supply Rejection Ratio            | VIN = 6 V, V <sub>OUT</sub> = 3.0 V,                                        | , Iout = 30 mA, f = 1 kHz                                | PSRR                |       | 27   |          | dB                |
| Output Noise Voltage                    | V <sub>OUT</sub> = 3.0 V, I <sub>OUT</sub> = 30 mA, f = 10 Hz to<br>100 kHz |                                                          | VN                  |       | 112  |          | μV <sub>rms</sub> |

#### **ELECTRICAL CHARACTERISTICS** T<sub>A</sub> = 25°C

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Dropout voltage for 2.0 V  $\leq$  V<sub>OUT</sub> < 3.7 V can be computed by this formula: V<sub>DO</sub> = 4 V - V<sub>OUTSET</sub>

















## **APPLICATION INFORMATION**

A typical application circuit for NCP4641 series is shown in Figure 32.



Figure 32. Typical Application Schematic

#### Input Decoupling Capacitor (C1)

The device is stable without any input capacitance, but if input line is long and has high impedance or if more stable operation is needed, input capacitor C1 should be connected as close as possible to the IC. Recommended range of input capacitor value is 100 nF to 10  $\mu$ F.

#### **Output Decoupling Capacitor (C2)**

The NCP4641 can work stable without output capacitor, but if faster response and higher stability reserve is needed, output capacitor should be connected as close as possible to the device. Recommended range of output capacitance is 100 nF to 10  $\mu$ F. Larger values of output capacitance and lower ESR improves dynamic parameters.

#### **Enable Operation**

**ORDERING INFORMATION** 

The enable pin CE may be used for turning the regulator on and off. The device is activated when high level is connected to CE pin. Do not keep CE pin not connected or between VCEH and VCEL voltage levels. Otherwise output voltage would be unstable or indefinite and unexpected would flow internally.

#### Thermal

As a power across the IC increase, it might become necessary to provide some thermal relief. The maximum power dissipation supported by the device is dependent upon board design and layout. Mounting pad configuration on the PCB, the board material, and also the ambient temperature affect the rate of temperature increase for the part. When the device has good thermal conductivity through the PCB the junction temperature will be relatively low in high power dissipation applications.

The IC includes internal thermal shutdown circuit that stops operation of regulator, if junction temperature is higher than 150°C. After that, when junction temperature decreases below 125°C, the operation of voltage regulator would restart. While high power dissipation condition is, the regulator starts and stops repeatedly and protects itself against overheating.

#### **PCB Layout**

Pins number 2 and 4 of SOT89–5 package and pins number 2, 4 and 5 of SOIC6–TL must be wired to the GND plane while it is mounted on board. Make VIN and GND lines sufficient. If their impedance is high, noise pickup or unstable operation may result. Connect capacitors C1 and C2 as close as possible to the IC, and make wiring as short as possible.

| Device         | Nominal Output<br>Voltage | Description | Marking | Package               | Shipping <sup>†</sup> |
|----------------|---------------------------|-------------|---------|-----------------------|-----------------------|
| NCP4641H030T1G | 3.0 V                     | Enable High | M030    | SOT89–5<br>(Pb–Free)  | 1000 / Tape & Reel    |
| NCP4641H033T1G | 3.3 V                     | Enable High | M033    | SOT-89-5<br>(Pb-Free) | 1000 / Tape & Reel    |
| NCP4641H050T1G | 5.0 V                     | Enable High | M050    | SOT89–5<br>(Pb–Free)  | 1000 / Tape & Reel    |
| NCP4641H080T1G | 8.0 V                     | Enable High | M080    | SOT89–5<br>(Pb–Free)  | 1000 / Tape & Reel    |

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*To order other package and voltage variants, please contact your ON Semiconductor sales representative.

#### PACKAGE DIMENSIONS

#### SOIC6 (HSOP6) CASE 751BR

**ISSUE A** 









#### RECOMMENDED SOLDERING FOOTPRINT\*



NOTES:

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS 3. DIMENSION & AND &1 DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWAQBLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION
- CONDITION. 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS, MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F. DATUMS A AND B ARE DETERMINED AT DATUM F. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- 5. 6.

| PUINT | OINT ON THE PACKAGE |      |  |  |  |
|-------|---------------------|------|--|--|--|
|       | MILLIMETERS         |      |  |  |  |
| DIM   | MIN                 | MAX  |  |  |  |
| Α     | 1.45                | 1.85 |  |  |  |
| A1    | 0.05                | 0.25 |  |  |  |
| A3    | 0.15                | 0.30 |  |  |  |
| b     | 0.30                | 0.50 |  |  |  |
| b1    | 1.57                | 1.77 |  |  |  |
| D     | 4.72                | 5.32 |  |  |  |
| E     | 3.70                | 4.10 |  |  |  |
| е     | 3.81                | BSC  |  |  |  |
| н     | 5.70                | 6.30 |  |  |  |
| L     | 0.40                | 0.80 |  |  |  |
| L2    | 0.25                | BSC  |  |  |  |
| L2    | 0.25                | BSC  |  |  |  |

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

SOT-89, 5 LEAD CASE 528AB

**ISSUE O** 



TOP VIEW



NOTES

- 1. DIMENSIONING AND TOLERANCING PER ASME 2. CONTROLLING DIMENSION: MILLIMETERS.
- LEAD THICKNESS INCLUDES LEAD FINISH. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. 4.
- 5. DIMENSIONS L, L2, L3, L4, L5, AND H ARE MEA-SURED AT DATUM PLANE C.

|     | MILLIMETERS |      |  |  |
|-----|-------------|------|--|--|
| DIM | MIN MAX     |      |  |  |
| Α   | 1.40        | 1.60 |  |  |
| b   | 0.32        | 0.52 |  |  |
| b1  | 0.37        | 0.57 |  |  |
| С   | 0.30        | 0.50 |  |  |
| D   | 4.40        | 4.60 |  |  |
| D2  | 1.40        | 1.80 |  |  |
| Е   | 2.40        | 2.60 |  |  |
| е   | 1.40        | 1.60 |  |  |
| н   | 4.25        | 4.45 |  |  |
| L   | 1.10        | 1.50 |  |  |
| L2  | 0.80        | 1.20 |  |  |
| L3  | 0.95        | 1.35 |  |  |
| L4  | 0.65        | 1.05 |  |  |
| L5  | 0.20        | 0.60 |  |  |



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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